

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): KAJIHARA, et al.
Serial No.: 09/987,978
Filed: November 16, 2001
For: LEADFRAME SEMICONDUCTOR INTEGRATED CIRCUIT
DEVICE USING THE SAME, AND METHOD OF AND
PROCESS FOR FABRICATING THE TWO
Group: 2815
Examiner: Jasmine Jhihan B Clark
Conf. No.: 7905

**PETITION FOR WITHDRAWAL OF ERRONEOUS
HOLDING OF ABANDONMENT**

Mail Stop: Amendment (No Fee)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

March 3, 2010

Sir:

Applicant, through its undersigned attorney, acknowledges receipt of a notice of abandonment mailed December 18, 2009, in connection with the above-identified application. However, since the notice of abandonment is in error, withdrawal of the erroneous holding of abandonment is requested.

The notice of abandonment indicates the application to be abandon for failure to respond to the office action of May 14, 2009. However, a response to the office action was filed on November 16, 2009 with appropriate extension fees. A copy of the Amendment, Extension of Time and Electronic Acknowledgement Receipt from the US Patent Trademark Office, evidencing receipt of the Amendment in the United States Patent and Trademark Office on November 16, 2009 are attached. Since the

response was timely filed, the notice of abandonment is in error and should be withdrawn.

Please charge any shortage in the fees due in connection with the filing of this paper, to the deposit account of Antonelli, Terry, Stout & Kraus, LLP, Deposit Account No. 01-2135 (Case No. 1374.32049RV1), and please credit any excess fees to such deposit account.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

/Paul J. Skwierawski/
Paul J. Skwierawski
Registration No. 32,173

PJS/slk
(703) 312-6600
Attachments

Electronic Acknowledgement Receipt

EFS ID:	6460491
Application Number:	09987978
International Application Number:	
Confirmation Number:	7905
Title of Invention:	LEADFRAME SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE USING THE SAME, AND METHOD OF AND PROCESS FOR FABRICATING THE TWO
First Named Inventor/Applicant Name:	Yujiro Kajihara
Customer Number:	20457
Filer:	Paul J. Skwierawski/Stacey Keaton
Filer Authorized By:	Paul J. Skwierawski
Attorney Docket Number:	1374.32049RV1
Receipt Date:	16-NOV-2009
Filing Date:	16-NOV-2001
Time Stamp:	15:34:53
Application Type:	Utility under 35 USC 111(a)

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Deposit Account	
Authorized User	

File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
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1	Amendment/Req. Reconsideration-After Non-Final Reject	32049RV1amd.pdf	130911 691ab7bd631e85548d459dc5fe3ca6b3761 b48bb	no	14
Warnings:					
Information:					
2	Extension of Time	32049RV1eot.pdf	56553 63324732001bc228cd98480a5e7ef99bbe4 aa087	no	1
Warnings:					
Information:					
3	Fee Worksheet (PTO-875)	fee-info.pdf	31110 8814e3485a2a6d06c039fef32a91cc23abdc ae97	no	2
Warnings:					
Information:					
Total Files Size (in bytes):			218574		
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><u>New Applications Under 35 U.S.C. 111</u> If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><u>National Stage of an International Application under 35 U.S.C. 371</u> If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p><u>New International Application Filed with the USPTO as a Receiving Office</u> If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>					

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Group: 2815

Examiner: Jasmine Jhihan B Clark

Conf. No.: 7905

PETITION FOR EXTENSION OF TIME

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

November 16, 2009

Sir:

In the matter of the above-identified application, applicants hereby respectfully petition for an extension of time to permit filing a response within the third month subsequent to expiration of the shortened statutory period set in the outstanding Office Action mailed May 14, 2009. An electronic payment in the amount of \$1,110.00 to cover the required fee for the requested extension of time is being submitted herewith.

It is respectfully requested that any shortage in the fee be charged to the account of Antonelli, Terry, Stout & Kraus, LLP, Account No. 01-2135 (Case No. 1374.32049RV1).

Respectfully submitted,
ANTONELLI, TERRY STOUT & KRAUS, LLP

/Paul J. Skwierawski/
Paul J. Skwierawski
Registration No. 32,173

PJS/slk

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AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

16 November 2009

Sir:

In response to the 14 May 2009 Office Action, please amend the above-identified application as listed below and as set forth on the following pages:

Amendments to the Specification

Amendments to the Claims

Remarks are included following the amendments

Amendments to the Specification:

Please amend the paragraph at Column 1, lines 5-7, as follows:

Notice: More than one reissue application has been filed for the reissue of USP 5,637,913. The reissue cases are Application No. 09/328,910 filed 9 June 1999, pending, and its divisions, Application No. 09/987,978 filed 16 November 2001 (the present case), pending, and Application No. 09/989,242 filed 21 November 2001, pending. This application Serial No. 09/987,978, filed November 16, 2001, is a divisional application of Serial No. 09/328,910, filed June 9, 1999.

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1.-14. (Cancelled)

15. (Currently Amended) A semiconductor device comprising:

(a) a semiconductor chip having a plurality of semiconductor elements and bonding pads formed on a main surface thereof;

(b) a lead frame having:

a chip mounting portion having one surface for mounting said semiconductor chip;

suspension leads continuously formed with said chip mounting portion; and
a plurality of leads each having an inner lead portion and an outer lead portion continuously formed with said inner lead portion and being arranged at a periphery of said chip mounting portion, said inner lead portions of said plurality of leads being electrically connected with said bonding pads of said semiconductor chip; and

(c) a resin member sealing said semiconductor chip, said chip mounting portion and said inner lead portions of said plurality of leads,

wherein a size of said chip mounting portion is smaller than that of said semiconductor chip, and

wherein said one surface of said chip mounting portion is a surface on which burrs are not formed, during formation of said chip mounting portion,

wherein said chip mounting portion is positioned under a substantially central portion of said semiconductor chip.

wherein said semiconductor chip is fixed to said chip mounting portion by an adhesive.

wherein said semiconductor chip is fixed to a part of each of suspension leads by an adhesive, and

wherein said suspension leads and said chip mounting portion of said lead frame are continuously formed in an area of said semiconductor chip.

16. (Previously Presented) A semiconductor device according to Claim 15, wherein said burrs are formed when said lead frame is made by pressing.

17. (Previously Presented) A semiconductor device according to Claim 15, wherein said chip mounting portion has a substantially circular form in a plane view.

18. (Previously Presented) A semiconductor device according to Claim 16, wherein said chip mounting portion has a substantially cross form in a plane view.

19. (Previously Presented) A semiconductor device according to Claim 15, wherein said inner lead portions of said plurality of leads are electrically connected with said bonding pads of said semiconductor chip by a plurality of bonding wires.

20. (Previously Presented) A semiconductor device according to Claim 19,
wherein parts of said inner lead portions of said plurality of leads, to which said
plurality of bonding wires are connected, are plated.

21. (Currently Amended) A semiconductor device comprising:

(a) a semiconductor chip having a plurality of semiconductor elements and
bonding pads formed on a main surface thereof;

(b) a lead frame having:

a chip mounting portion for mounting said semiconductor chip;
suspension leads continuously formed with said chip mounting portion; and
a plurality of leads each having an inner lead portion and an outer lead portion
continuously formed with said inner lead portion and being arranged at a periphery of
said chip mounting portion.

(c) a plurality of bonding wires electrically connecting said inner lead portions
of said plurality of leads with said bonding pads of said semiconductor chip
respectively, each of said inner lead portions of said plurality of leads having one
surface to which a corresponding bonding wire among said plurality of bonding wires
is connected; and

(d) a resin member sealing said semiconductor chip, said plurality of bonding
wires, said chip mounting portion and said inner lead portions of said plurality of
leads,

wherein said one surface of said inner lead portion of each of said plurality of
leads is a surface on which burrs are not formed, said burrs being resultant from
formation of said plurality of leads.

wherein said chip mounting portion is positioned under a substantially central portion of said semiconductor chip.

wherein said semiconductor chip is fixed to said chip mounting portion by an adhesive.

wherein said semiconductor chip is fixed to a part of each of suspension leads by an adhesive, and

wherein said suspension leads and said chip mounting portion of said lead frame are continuously formed in an area of said semiconductor chip.

22. (Previously Presented) A semiconductor device according to Claim 21, wherein a size of said chip mounting portion is smaller than that of said semiconductor chip.

23. (Previously Presented) A semiconductor device according to Claim 21, wherein said burrs are formed when said lead frame is made by pressing.

24. (Previously Presented) A semiconductor device according to Claim 22, wherein said chip mounting portion has a substantially circular form in a plane view.

25. (Previously Presented) A semiconductor device according to Claim 22, wherein said chip mounting portion has a substantially cross form in a plane view.

26. (Currently Amended) A semiconductor device comprising:

(a) a semiconductor chip having a plurality of semiconductor elements and bonding pads formed on a main surface thereof;

(b) a lead frame having:

a chip mounting portion having a first surface for mounting said semiconductor chip;

suspension leads continuously formed with said chip mounting portion; and

a plurality of leads each having an inner lead portion and an outer lead portion continuously formed with said inner lead portion and being arranged at a periphery of said chip mounting portion;

(c) a plurality of bonding wires electrically connecting said inner lead portions of said plurality of leads with said bonding pads of said semiconductor chip respectively, each of said inner lead portions of said plurality of leads having a second surface to which a corresponding bonding wire among said plurality of bonding wires is connected; and

(d) a resin member sealing said semiconductor chip, said plurality of bonding wires, said chip mounting portion and said inner lead portions of said plurality of leads,

wherein a size of said chip mounting portion is smaller than that of said semiconductor chip,

wherein said first surface of said chip mounting portion is a surface on which burrs are not formed, and

wherein said second surface of said inner lead portion of each of said plurality of leads is a surface on which said burrs are formed, said burrs resultant from formation of said chip mounting portion and said plurality of leads,

wherein said chip mounting portion is positioned under a substantially central portion of said semiconductor chip,

wherein said semiconductor chip is fixed to said chip mounting portion by an adhesive,

wherein said semiconductor chip is fixed to a part of each of suspension leads by an adhesive, and

wherein said suspension leads and said chip mounting portion of said lead frame are continuously formed in an area of said semiconductor chip.

27. (Cancelled)

REMARKS

This paper is responsive to any paper(s) indicated above, and is responsive in any other manner indicated below.

SUPPLEMENTAL REISSUE OATH/DECLARATION

The reissue oath/declaration has been objected to based upon the Office Action concern(s) as set forth within the Office Action. MPEP 1444's section II indicates that Applicant is able to defer the filing of a Supplemental Reissue Oath/Declaration until the end of prosecution). Applicant is presently in the process of having the inventor(s) execute a Reissue Oath/Declaration covering all presently-existing reissue errors and/or all papers submitted to date (including this paper), and such executed Reissue Oath/Declaration will be submitted shortly. That is, Applicant purposefully is having a Reissue Oath/Declaration executed subsequent to submission of this present Amendment, so that such Reissue Oath/Declaration can be comprehensive to cover amendments submitted (i.e., errors corrected) with this present Amendment, and obviate any need for another supplemental Reissue Oath/Declaration. If the Reissue Oath/Declaration becomes the only issue barring allowance of the application, the Examiner is asked to please refrain from issuing another action, and instead is invited to call the undersigned at the local Washington, D.C. telephone number of 703-312-6600 to provoke accelerated filing of such document to move the application to allowance.

WRITTEN CONSENT OF ASSIGNEE

The Written Consent Of Assignee has been objected to based upon the Office Action concern(s) as set forth within the Office Action. Traversal is appropriate. However, to travel a path of least resistance to grant of a patent, Applicant is **presently in the process of having the Assignee execute another Written Consent of Assignee (at the same time the Reissue Oath/Declaration mentioned above is being executed)** to cover amendments submitted (i.e., errors corrected) with this present Amendment, and **obviate any need for another supplemental Written Consent Of Assignee.** If the Written Consent Of Assignee becomes the only issue barring allowance of the application, **the Examiner is asked to please refrain from issuing another action, and instead is invited to call the undersigned at the local Washington, D.C. telephone number of 703-312-6600 to provoke accelerated filing of the of such document** to move the application to allowance.

PENDING CLAIMS

Claims 15-26 were pending, under consideration and subjected to examination in the Office Action. Appropriate claims have been amended, canceled and/or added (without prejudice or disclaimer) in order to adjust a clarity and/or focus of Applicant's claimed invention. That is, such changes are unrelated to any prior art or scope adjustment and are simply refocused claims in which Applicant is present interested. At entry of this paper, Claims 15-26 will be pending for further consideration and examination in the application.

REISSUE BROADENING – TWO-YEAR BAR

The paragraph numbered "1" on "Page 3" of at least the 14 May 2009 Office Action states (in part): "Clarification is needed as to the claiming of benefit to copending reissue 09/328910. This reissue should be claimed as a division of 09/328910, otherwise the two-year bar against the reissue application broadening invention applies." **Strong traversal is appropriate.**

More particularly, a portion of **MPEP Section 1412.03**, subsection "**IV WHEN A BROADENED CLAIM CAN BE PRESENTED**", page 1400-29, Rev. 7, July 2008, is reproduced and highlighted herewith, as follows:

SECTION OF PATENTS

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Thus, a broadened claim may be presented in a reissue application after the two years, even though the broadened claim presented after the two years is different than the broadened claim presented within the two years. Finally, if intent to broaden is indicated in a parent reissue application within the two years, a broadened claim can be presented in a continuing (continuation or divisional) reissue application after the two year period. In any other situation, a broadened claim cannot be presented, and the examiner should check carefully for the improper presentation of broadened claims.

A reissue application filed on the 2-year anniver-

Given that Applicant's parent (original) reissue application indicated an intent to, and did in fact, broaden within two years from the grant of the original patent, and given the fact that Applicant claims 120 priority from such parent (original) reissue application, it is respectfully submitted that broadening is

permitted within the present application (whether it is a **CONTINUATION** application **or DIVISIONAL** application). Accordingly, reconsideration and withdrawal of any rejection of Applicant's claim(s) based upon the two-year (2-year) broadening bar, are respectfully requested.

In order to travel a path of least resistance to issuance of a patent, an opening portion of Applicant's specification has been amended (without prejudice/disclaimer) at this time to label the present application as a "Divisional" of the parent (original) reissue application. In the event that the Examiner decides that "Continuation" is a more appropriate label, the Examiner is herein authorized to change such label by examiner's amendment.

RECAPTURE REJECTION - TRAVERSED

The recapture rejection of ones of Applicant's claims as set forth beginning on page 4 of the Office Action (and/or within prior Office Actions) is respectfully traversed.

As an aside, it is respectfully noted that Applicant's application at the time of the 14 May 2009 Office Action included only claims 15-26, whereas it is noted that page 4 of such Office Action contains errors, in that such page discusses claims 29, 49, 53 and 54 which are not included within the present application (but may have instead been included within a co-pending reissue application related to the present application). Applicant respectfully requests that any subsequent actions concerning the present application, accurately list claims existing within the application.

In spite of traversal, the recapture rejection of **claims 15-26** is presently **obviated** owing to such claims being **amended (or written) to include the**

disputed recapture limitations. Such amendment or rewriting (without prejudice or disclaimer), should not be taken as an indication or admission that the objection or rejection was valid, or as a disclaimer of any scope or subject matter, but is merely lessening of a number of claims having alleged recapture concerns, to lessen a number of issues so as to move prosecution toward allowance more quickly. Reconsideration and allowance of such claims, are respectfully requested.

EXAMINER INVITED TO TELEPHONE

The Examiner is herein invited to telephone the undersigned attorneys at the local Washington, D.C. area telephone number of 703/312-6600 for discussing any Examiner's Amendments or other suggested actions for accelerating prosecution and moving the present application to allowance.

RESERVATION OF RIGHTS

It is respectfully submitted that any and all claim amendments and/or cancellations submitted within this paper and throughout prosecution of the present application are without prejudice or disclaimer. That is, any above statements, or any present amendment or cancellation of claims (all made without prejudice or disclaimer), should not be taken as an indication or admission that any objection/rejection was valid, or as a disclaimer of any scope or subject matter. Applicant respectfully reserves all rights to file subsequent related application(s) (including reissue applications) directed to any/all previously claimed limitations/features which have been subsequently amended or cancelled, or to any/all limitations/features not yet claimed, i.e., Applicant continues (indefinitely) to

maintain no intention or desire to dedicate or surrender any limitations/features of subject matter of the present application to the public.

CONCLUSION

In view of the foregoing amendments and remarks, Applicant respectfully submits that the application is now in condition for allowance.

To the extent necessary, Applicant petitions for an extension of time under 37 CFR '1.136. Authorization is herein given to charge any shortage in the fees, including extension of time fees and excess claim fees, to Deposit Account No. 01-2135 (Case No. 1374.32049RV1) and please credit any excess fees to such deposit account.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

/Paul J. Skwierawski/
Paul J. Skwierawski
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